



BGA/CSP DEVELOPMENT UPDATE SERVICE

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The fourth quarterly BGA/CSP update for 2001 features special coverage of the market forecast for BGAs and CSPs. Breakouts for CSP unit volumes of flex-based, rigid (laminated and ceramic) substrate, and lead frame type packages are included. The update provides a forecast for wafer level packages in number of wafers. BGA unit volumes are provided in PBGAs, TBGAs, and CBGAs/CCGAs with an additional category for Bluetooth® type modules. Growth in the market is analyzed in light of the worldwide economic recession. Products using CSPs and BGAs are detailed, including numerous color photos, and major application areas. The update also gives an analysis of major device types and package choices. Highlighted are ASICs, programmable logic devices (PLDs), microprocessors, chipsets, graphics chips, and digital signal processors.

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